

CLAIMS

What is claimed is:

- 1 1. A system for lapping a head, comprising:
 - 2 (a) a wafer including at least one head each having an electrical lapping guide (ELG),
3 a plurality of wafer contacts in electrical communication with the ELG, and a
4 closure formed thereon defining a slot in which the wafer contacts are positioned;
 - 5 (b) a lapping cable coupled to a testing device, the lapping cable including a plurality
6 of lapping cable contacts; and
 - 7 (c) an adapter including a plurality of adapter contacts in electrical communication
8 with the lapping cable contacts;
 - 9 (d) wherein the adapter contacts are removably positionable in electrical
10 communication with the wafer contacts during a lapping process.
- 1 2. The system as recited in claim 1, wherein the adapter is constructed from a
2 polyimide material.
- 1 3. The system as recited in claim 1, wherein adapter includes a pair of holes formed
2 therein for coupling with a pair of holes formed in the lapping cable via a pair of
3 alignment pins.

- 1 4. The system as recited in claim 1, wherein the adapter includes at least one guide
2 for being removably positioned in a slot defined by closures of adjacent heads
3 formed on the wafer.

- 1 5. The system as recited in claim 1, wherein the adapter contacts are slidably
2 coupled to the adapter.

- 1 6. The system as recited in claim 1, wherein the adapter contacts each include a first
2 portion in electrical communication with one of the lapping cable contacts and a
3 second portion in electrical communication with one of the wafer contacts.

- 1 7. The system as recited in claim 6, wherein the first portion of each adapter contact
2 is larger than the second portion of each adapter contact.

- 1 8. The system as recited in claim 7, wherein the first portion of each adapter contact
2 has a diameter larger than that of the second portion of each adapter contact.

- 1 9. The system as recited in claim 6, wherein the adapter includes a recess for
2 preventing contact with the wafer during the lapping process.

- 1 10. An system for lapping a head, comprising:

- 2 (a) a wafer including at least one head each having an electrical lapping guide (ELG),
3 a plurality of wafer contacts in electrical communication with the ELG, and a
4 closure formed thereon defining a slot in which the wafer contacts are positioned;
5 and
- 6 (b) a lapping cable coupled to a testing device, the lapping cable including a plurality
7 of lapping cable contacts extending outwardly therefrom;
- 8 (c) wherein the lapping cable contacts are removably positionable in electrical
9 communication with the wafer contacts during a lapping process.

1 11. The system as recited in claim 10, wherein the lapping cable includes at least one
2 guide for being removably positioned in a slot defined by closures of adjacent
3 heads formed on the wafer.

1 12. The system as recited in claim 10, wherein the lapping cable contacts extend in a
2 direction perpendicular with respect to the lapping cable.

1 13. The system as recited in claim 10, wherein the lapping cable includes a recess for
2 preventing contact with the wafer during the lapping process.

1 14. An apparatus for use with a wafer including at least one head each having an
2 electrical lapping guide (ELG), a plurality of wafer contacts in electrical
3 communication with the ELG, and a closure formed thereon defining a slot in
4 which the wafer contacts are positioned, and a lapping cable coupled to a testing

5 device, the lapping cable including a plurality of lapping cable contacts; the
6 apparatus comprising: an adapter including a plurality of adapter contacts in
7 electrical communication with the lapping cable contacts, wherein the adapter
8 contacts are removably positionable in electrical communication with the wafer
9 contacts during a lapping process.

- 1 15. An apparatus for use with a wafer including at least one head each having an
2 electrical lapping guide (ELG), a plurality of wafer contacts in electrical
3 communication with the ELG, and a closure formed thereon defining a slot in
4 which the wafer contacts are positioned, the apparatus comprising:
- 5 (a) a lapping cable coupled to a testing device, the lapping cable including a plurality
6 of lapping cable contacts extending outwardly therefrom in direction
7 perpendicular with respect to the lapping cable;
- 8 (b) wherein the lapping cable contacts are removably positionable in electrical
9 communication with the wafer contacts during a lapping process.

- 1 16. An adapter including a plurality of adapter contacts in electrical communication
2 with a plurality of lapping cable contacts of the lapping cable, wherein the adapter
3 contacts are removably positionable in electrical communication with a plurality
4 of wafer contacts of a wafer during a lapping process.

- 1 17. A lapping cable coupled to a testing device and including a plurality of lapping
2 cable contacts extending outwardly therefrom in a direction perpendicular with

3 respect to the lapping cable, wherein the lapping cable contacts are removably
4 positionable in electrical communication with a plurality of wafer contacts of a
5 wafer during a lapping process.

1 18. An adapter including a plurality of adapter contacts in electrical communication
2 with a plurality of lapping cable contacts of the lapping cable, the adapter further
3 including at least one guide for being removably positioned in a slot defined by
4 closures of adjacent heads formed on the wafer, and a recess for preventing
5 contact with the wafer during the lapping process, wherein the adapter contacts
6 are removably positionable in electrical communication with a plurality of wafer
7 contacts of the wafer during a lapping process.

1 19. A method for testing during a lapping process, comprising:
2 (a) providing an adapter including a plurality of adapter contacts in electrical
3 communication with a plurality of lapping cable contacts of the lapping cable;
4 (b) removably positioning the adapter contacts of the adapter in electrical
5 communication with a plurality of wafer contacts of a wafer;
6 (c) lapping a surface of the wafer; and
7 (d) measuring a head of the wafer during the lapping process.